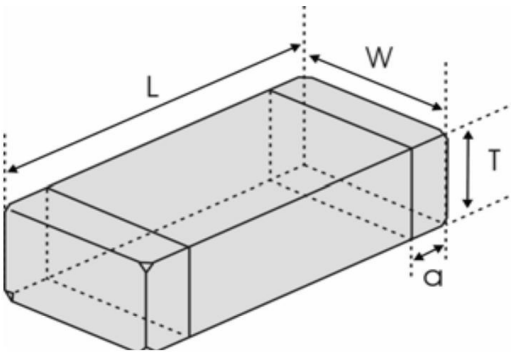
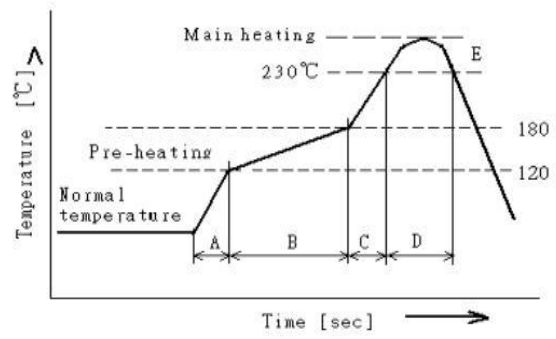
外观图/DIMENSION（单位/UNIT：mm）



L	W	T	a
1.6±0.15 [.063±.006]	0.8±0.15 [.031±.006]	0.8±0.15 [.031±.006]	0.3±0.2 [.012±.008]

电性能参数表 Electrical Characteristics List

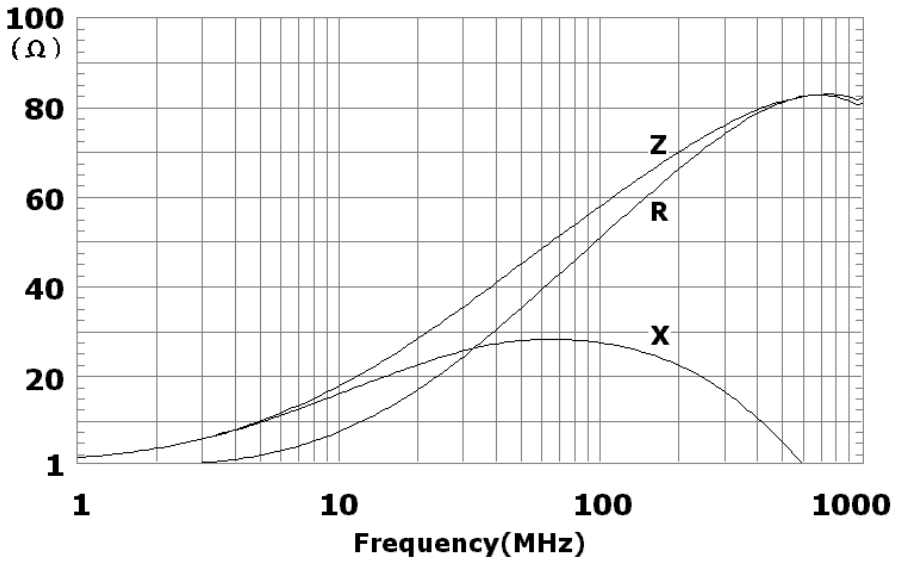
Temperature Profile



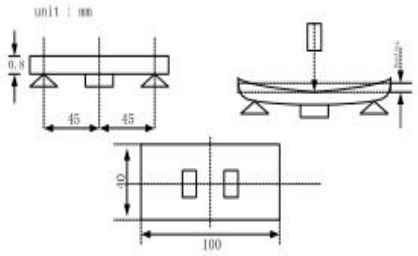
A	Slope of temp. rise	※ 1 to 5	※ ℃/sec
B	Heat time	50 to 150	※ sec
	Heat temperature	120 to 180	※ ℃
C	Slope of temp. rise	1 to 5	※ ℃/sec
D	Time over 230℃	90~120	※ sec
E	Peak temperature	255~260	※ ℃
	Peak hold time	10 max.	※ sec
※ No. of mounting		3	※ times

PART NUMBER	IMPEDANCE(Ω)	TEST FREQUENCY (MHz)	MAX.DC.RESISTANCE(Ω)	MAX.RATED CURRENT (mA)
LMTCZ1608-60R-3A	60±25%	100	0.04	3000

※工作温度范围 Operating temperature range: -45℃~+125℃
※储存温度范围 Storage temperature range: -10℃~+40℃, 70% RH.a.
测试环境条件 Test Conditions
一般按照以下环境条件测试（有特殊要求的除外），：
Unless otherwise specified, the standard atmospheric conditions for measurement/test as:
※温度 Ambient Temperature: 20±15℃
※ 湿度 Relative Humidity: 65±20%
※ 大气压 Air Pressure: 86 kPa to 106 kPa



测试及可靠性 Testing and reliability

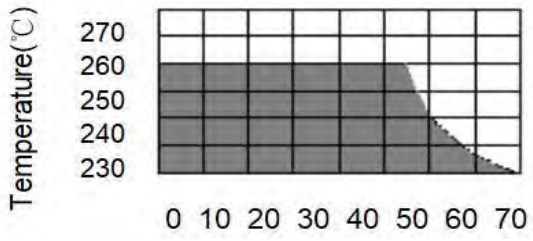
焊锡Solder：Sn-3Ag-0.5Cu	
弯曲 Bend	试验后无破损现象，电感量应在±20%以unit：mm内，直流电阻应符合标准/规范要求。 Without deformation cases， Inductance shall be satisfied±20%， DC resistance shall be satisfied. 将产品焊接在试验板上，如图所示在试验板中间位置施加压力，使得试验板中心点向下弯曲2mm， 保持10秒。After soldering a chip to a test substrate， bend the substrate by 2mm hod for10s and then retum. Soldering shall be done in accordance wt the recommended PC board pattern and reflow soldering. 
振动 Vibration	a.试验要求Performance specification1) 外观Appearance：无可见机械损伤no mechanical damage2) 电感量变化应在+20%以内Inductance shall be wth±20%of the intal value b.试验条件Test condition1) 波形Waveform：正弦波Sinewave2)频率Frequency：10~55~10Hz3) 持续时间Sweep t me：1min4)Amplitude：1.5mm(peak-peak)5.Direction：X， Y， Z(3axes)6.Duration：2hrs./axis，total 6hrs.
温度冲击 Temperature shock	a.试验要求Performance specification1) 外观Appearance：无可见机械损伤no mechanical damage2) 电感量变化应在±20%以内Inductance shall be with+20%of the initialvalue b.试验条件Test condition1) 温度Temperature：-45℃， +125℃各保持30分钟。-45℃， +125℃keptstabiizedfor30 minutes each2)周期Cycle：5次。5cycles.3) 检查Measurement：试验后至少在室温条件下放置24小时以上。After placing at room ambienttemperature for 24 hours minimum.

焊锡Solder：Sn-3Ag-0.5Cu	
湿热负载 HUMIDITYRESISTANCE	a.试验要求Performance specification1) 外观Appearance：无可见机械损伤no mechanical damage2) 电感量变化应在±20%以内Induct an cc shall be with+20%of the initialvalue b.试验条件Test condition1)湿度Humidity：90to95%RH2)温度Temperature：60+2℃3) 加载电流Applied current：额定直流电流Rated current4)试验时间Testingtinc：1000(+48，0)hours5) 检查Mca surement：试验后至少在室温条件下放置24小时以上。After placing at room ambienttemperature for 24 hours minimum.
高温负载 HIGHTEMPERATURERESISTANCE	a.试验要求Performance specificationl) 外观Appearance：无可见机械损伤no mechanical damage2) 电感量变化应在+20%以内Inductance shall be wth±20%of the in it lvalue b.试验条件Test condtion1) 温度Temperature：+125℃+2℃2) 加载电流Applied current：额定直流电流Rated current3)试验时间Testingtime：1000(+48，0)hours4) 检查Measurement：试验后至少在室温条件下放置24小时以上。After placing at room ambienttemperature for 24 hours minimum.
低温储存 LOWTEMPERATURESTORAGE LIFE	a.试验要求Performance specification1) 外观Appearance：无可见机械损伤no mechanical damage.2) 电感量变化应在±20%以内Inductance shall be with+20%of the initialvalue. b.试验条件Test condition 1.温度Temperature：-45℃+2℃ 2.试验时间Testingtime：1000(+48，0)hours3.检查Measurement：试验后至少在室温条件下放置24小时以上。After placing for 24 hours minimumat room ambient temperature.

测试及可靠性 Testing and reliability

焊锡Solder： Sn-3Ag-0.5Cu	
端头强度 TERMINALSTRENGTH	无破损现象。Without deformation cases.电感量变化应在±20%以内。Induct an cc shall be sat is fi cd±20%. 直流电阻应满足标准要求。DC resistance shall be satisfied.F焊接在PCB上的产品应持续成熟10N推力共10秒，0603[0201] 产品推力为2N。Solder chip on PCB and applied 10N(1.02Kgffor10scc.0603[0201] chip applied 2N. 
跌落 Drop	试验后产品应无失效现象。Products shall be no failure after test.产品跌落在混凝土地面或钢板上。It shall be dropped on concrete or steel board.试验方法：自由落下。Method：freefall.高度Height：100cm.产品跌落方向：3个方向。Att tude from which the product is dropped ： 3 direction.总次数：每个方向3次(共9次) 。The number of times ： 3 times for each direction(Total 9 times).
盐雾 Salt mist	a.试验要求Performance specification1) 外观Appearance：无可见机械损伤no mechanical damage.2) 电感量变化应在±20%以内Inductance shall be with±20%of the initialvalue. b.试验条件Test condtion1) 盐溶液溶度Concentration of salt solution：(5±0.1)%.2)PH：6.5-7.23)时间Time：48±2h
回流焊条件 Reflow soldering conditions	焊接之前产品应预热到 150℃。焊接后应冷却到 100℃。Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150℃ max.Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100℃ max.如果预热不充分，会导致产品质量恶化。Unenough pre－heating may cause cracks on the ferrite, resulting in the deterioration of product quality.产品应当按照下述曲线焊接。Products should be soldered within the following allowable range indicated by the slanted line.作业前，应对焊锡炉进行校准确认，保证能够符合焊接工艺条件。The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.

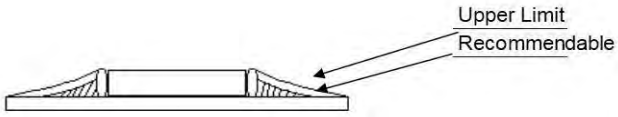
储存 Storage

储存 Storage	1.不得暴露在高温高湿环境下储存，否则导致产品外电极和焊接性恶化变差。建议包装好的产品储存在低于 40℃、小于 70% RH 条件下。The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40℃ or less and 70％RH or less. 2.不得暴露在灰尘或腐蚀性气体（如氯化氢，亚硫酸气体或硫化氢等）环境下储存，否则会导致产品外电极和焊接性恶化变差。The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide). 3.如果暴露在阳光直射或加热环境下储存，会导致包装材料变形。Packaging material may be deformed if packages are stored where they are exposed to heat or 4.采用聚乙烯热封载带形式的最小包装，在使用之前不要拆开。如果拆开了，应尽快使用卷盘保护起来。Minimum packages, such as polyvinyl heat-seal packages shall not be opened until just before they are used.If opened, use the reels as soon as possible. 5. 在符合1和 2要求的环境下储存，从产品发货日期开始 6 个月内，产品的焊接性能够满足规定的要求。Solderability specified in composite specification shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 1 & 2在产品使用之前，如果储存期超过 6 个月，则需要复检焊接性。For those parts which passed more than 6 months : is used. 

返工 Reworking with soldering iron	

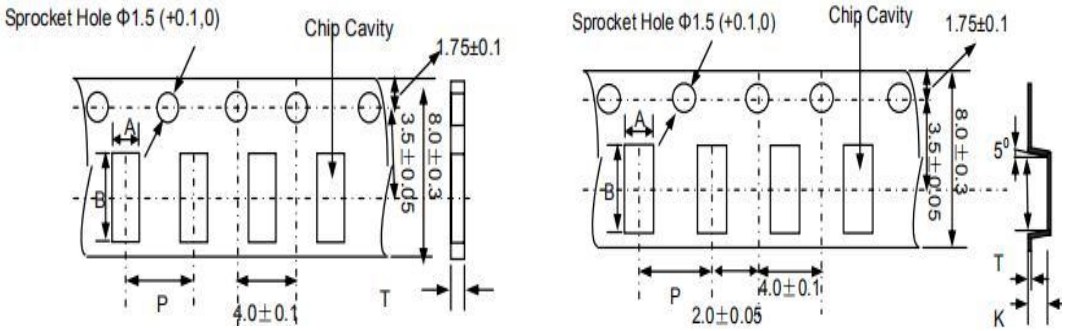
预热Preheating	150℃，1 minute
最高温度Tip temperature	280℃max
焊接时间Soldering time	3 seconds max.
电烙铁输出功率Soldering iron output	30wmax.
电烙铁焊头尺寸End of soldering iron	f3mmmax.

返工仅限一次。Reworking should be limited to only one time.
注意Note:为了避免焊接高温冲击导致产品本体开裂，电烙铁焊头焊锡时应避免直接与产品接触。Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.
9.3焊料量Solder Volume
焊料使用时，不得超过如下所示的上限要求。Solder shall be used not to be exceed the upper limits as shown below.
Upper Limit
Recommendable

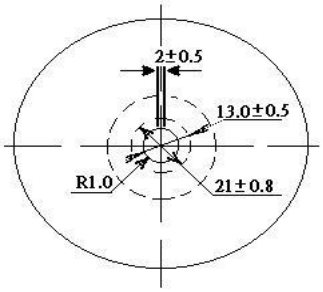


随若焊料的增加，产品承受的机械应力也随之增加。过量的焊料所产生的机械应力，会导致产品出现机械或电气特性失效。Accordingly increasing the solder volume,.the mechanical stress to product is also increased.Exceeding solder volume may cause the failure of mechanical or electrical performance.

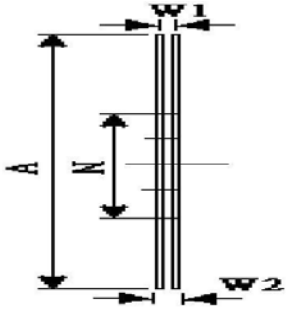
产品包装 Packaging



TYPE	A	B	P	Pmax	Tmax
1608	1.0±0.2	1.0±0.2	4.0±0.1	/	1.1

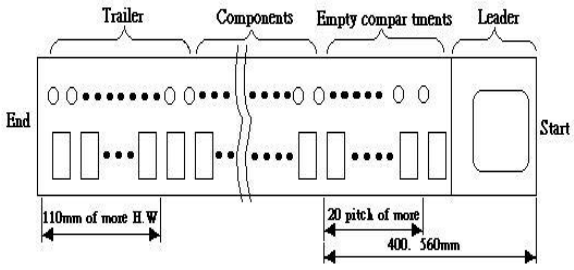


TYPE	1608
T（mm）	0.8±0.15
Tape	Paper Tape
Quantity	4000



UNIT:mm

A	178 ±2.0
N	50 MIN
W1	10 ±1.5
W2	20 MAX



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